

**REMARKS****INTRODUCTION**

Claims 1-8 are cancelled, claims 9-13 are newly added, and are therefore, pending.

Previously pending claims 1-8 were rejected under 35 USC § 102(e) because the Examiner believe that they were anticipated by U.S. Patent No. 6,562,521 issued to Nistler et al. ("Nistler"). These claims are no longer pending and as a result, this rejection is moot. However, pending claims 9-13 are patentable over Nistler because Nisltler fails to show or suggest the "sublayer" feature of the pending claims.

The Examiner states that Nistler's Figures 6-8 show evaluating the substrate in a cross section perpendicular to the lengthwise direction of the line section to observe the cross section (page 3, line 2 to 3). However, the Applicants respectfully disagree. Nistler's Figures 6-8 are top view and do not show evaluating the substrate in a cross section perpendicular to the lengthwise direction of the line section, as set forth in claim 11.

Pending claim 12 is also patentable for additional reasons. Nistler does not show that a plurality of photoresist patterns with reinforcing sections are formed such that lengthwise directions of line sections are parallel, and locations of reinforcing sections in the lengthwise direction of the line sections are different for adjacent photoresist patterns with reinforcing section. According to claim 12 of the present application, since locations of reinforcing section s in the lengthwise direction of the line sections are different for adjacent photoreist patterns with reinforcing section, when splitting the evaluation substrate, the cross section of the line section is always appears and the evaluation is made always possible. This effect is not disclosed in Nistler.

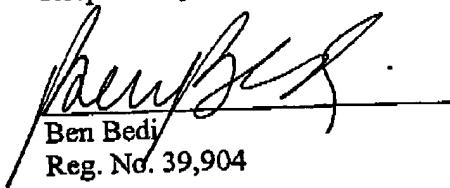
Similarly, claim 13 is also patentable for additional reasons. Specifically, Nistler does not show nor suggest a method of manufacturing a device, comprising forming on a substrate a photoresist pattern with a reinforcing section, wherein there is provided a line section and a reinforcing section that continues to said line section and that has a greater width than a line width of said line section, or a plurality of such reinforcing sections with spaces between themselves, by forming on the substrate a sublayer film that is soluble in a developing solution used in a developing process, forming on the sublayer film a photoresist

film, exposing the photoresist film, and developing the photoresist film by the developing solution.

**CONCLUSION**

Having addressed each and every ground of objection and rejection, applicants believe that the application is in condition for allowance. Applicants respectfully request reconsideration and allowance of the pending claims in the above-mentioned application and respectfully request that a timely Notice of Allowance be issued in this case.

Respectfully submitted,



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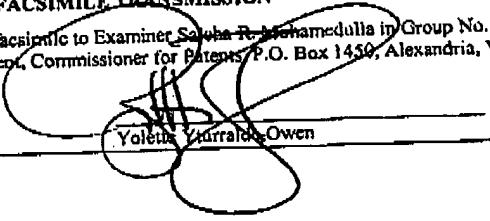
Dated: September 29, 2005

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**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being forwarded via facsimile to Examiner Sakiba R. Mohamedulla in Group No. 1756 at facsimile number (703) 872.9306 located at Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450, on

Date: September 29, 2005

  
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